

Simple Power Solution Using LDOs for the DM365

Ambreesh Tripathi

PMP - DC/DC Low Power Converters

ABSTRACT

This reference design is intended for users designing with TMS320DM365 Processor. This design is ideal for achieving the requirement of a input voltage of 5V, and uses LDOs for a simple, small configuration.

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1 Introduction

In dual voltage architectures, coordinated management of power supplies is necessary to avoid potential problems and ensure reliable performance. Power supply designers must consider the timing and voltage differences between core and I/O voltage supplies during power up and power down operations.

Sequencing refers to the order, timing and differential in which the two voltage rails are powered up and down. A system designed without proper sequencing may be at risk for two types of failures. The first of these represents a threat to the long term reliability of the dual voltage device, while the second is more immediate, with the possibility of damaging interface circuits in the processor or system devices such as memory, logic or data converter ICs.

Another potential problem with improper supply sequencing is bus contention. Bus contention is a condition when the processor and another device both attempt to control a bi-directional bus during power up. Bus contention may also affect I/O reliability. Power supply designers should check the requirements regarding bus contention for individual devices.



Power Requirements www.ti.com

2 Power Requirements

The power specifications and sequencing requirements for TMS320DM365 Processor is shown in the table below.

Table 1. TMS320DM365 Power Specs

	Pin Name	Voltage (V)	lmax (mA)	Tolerance	Sequencing Order
Core	CVDD, VDD12_PRTCSS, VDDA12_DAC, VPP	1.2 *	650	±5%	1
I/O	VDDS18, VDD18_PRTCSS, VDDMXI, VDD18_SLDO, VDD18_DDR, VDDA18_PLL, VDDA18_USB, VDDA18_VC, VDDA18_ADC, VDDA18_DAC	1.8	95	±5%	2
I/O	VDDS33, VDDA33_USB, VDDA33_VC	3.3	51	±5%	3
I/O	VDD_AEMIF1_18_3 3, VDD_AEMIF2_18_3 3, VDD_ISIF18_33	1.8 / 3.3	65	±5%	Ramp with appropriate voltage

Note:

- If running DM365 @ 300MHz, then CVDD, VDD12_PRTCSS, VDDA12_DAC and VPP = 1.35V and Imax = 800mA.
- If using PRTCSS, power-up sequencing changes to:
 - 1. Power on PRTCSS core (1.2-V) while RESET is low
 - 2. Power on PRTCSS I/O (1.8-V)
 - 3. Power on Main core (1.2-V)
 - 4. Power on Main I/O (1.8-V)
 - 5. Power on Main/Analog I/O (3.3-V)

3 Features

The design uses the following LDSOs.

Devices:	TPS74701(3.3V),TPS74801(1.2V),TPS74701(1.8V)				
Power supply specs:					
Vin	5 V ± 10%				
Vout1	1.2 V ± 5% at 800 mA				
Vout2	1.8 V \pm 5% at 200 mA				
Vout3	3.3 V \pm 5% at 200 mA				
Sequencing	1) Vout1 2) Vout2 3) Vout3				

TPS74801 and TPS74701

- VOUT Range: 0.8V to 3.6V
- 2% Accuracy Over Line/Load/Temperature
- Programmable Soft-Start Provides Linear Voltage Startup
- Stable with Any Output Capacitor ≥ 2.2μF
- Available in a Small 3mm × 3mm × 1mm SON-10 and 5 × 5 QFN-20 Packages

More information on the Devices can be found from the datasheets.

TPS74801 –<u>SBVS074F</u> TPS74701 –<u>SBVS099D</u>

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www.ti.com Features

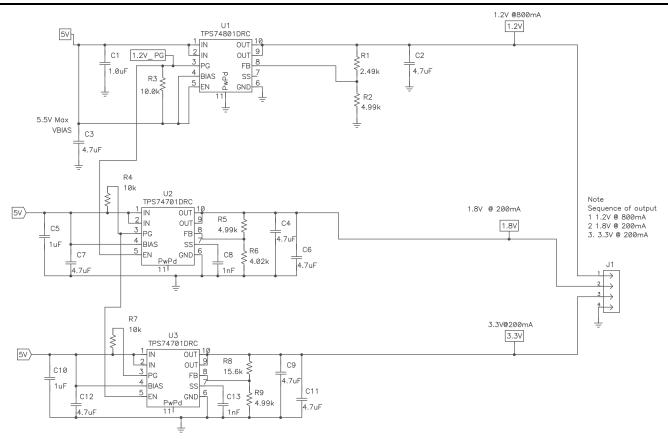


Figure 1. PMP5048 Reference Design Schematic

Proper sequencing is achieved in the design with the use of enable pins. The Core 1.2V at 800mA (TPS74801) comes first, PG output of the device then enable the TPS74701 (1.8V) device which in turn enable second TPS74701 (3.3V) device thus, following the required sequence.



List of Material www.ti.com

4 List of Material

Table 2. PMP5048 List of Materials

Count	RefDes	Value	Description	Size	Part Number	MFR	Area
1	C1	1.0 μF	Capacitor, Ceramic, 25V, X5R, 10%	0603	C1608X5R1E105K	TDK	5650
1	C2	4.7 μF	Capacitor, Ceramic, 6.3V, X5R, 10%	0603	C1608X5R0J106M	TDK	5650
1	C3	4.7 μF	Capacitor, Ceramic, 6.3V, X5R, 10%	0603	C1608X5R0J475K	TDK	5650
6	C4	4.7 μF	Capacitor, Ceramic,4.7 µF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
2	C5	1 μF	Capacitor, Ceramic,1 μF, 16V, X5R	0603	C1608X5R1C105K	TDK	5650
	C6	4.7 μF	Capacitor, Ceramic,4.7 µF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
	C7	4.7 μF	Capacitor, Ceramic,4.7 µF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
2	C8	1 nF	Capacitor, Ceramic, 1000 pF, 50V, X7R, 10%	0603	C1608X7R1H102K	TDK	5650
	C9	4.7 μF	Capacitor, Ceramic,4.7 µF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
	C10	1 μF	Capacitor, Ceramic,1 μF, 16V, X5R	0603	C1608X5R1C105K	TDK	5650
	C11	4.7 μF	Capacitor, Ceramic,4.7 μF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
	C12	4.7 μF	Capacitor, Ceramic,4.7 μF, 6.3V, X5R	0603	C1608X5R0J475M	TDK	5650
	C13	1 nF	Capacitor, Ceramic, 1000 pF, 50V, X7R, 10%	0603	C1608X7R1H102K	TDK	5650
1	J1	PEC36SAAN	Header, Male 4-pin, 100mil spacing, (36-pin strip)	0.100 inch x 4	PEC36SAAN	Sullins	50000
1	R1	2.49k	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650
1	R2	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650
1	R3	10.0k	Resistor, Chip, 1/16W, 1%	0603	Std	Std	5650
2	R4	10k	Resistor, Chip, 10kΩ 1/16W, 5%	0603	Std	Std	5,650
1	R5	4.99k	Resistor, Chip, 2k49Ω, 1/16W, 5%	0603	Std Std		5,650
1	R6	4.02k	Resistor, Chip, 4k99Ω, 1/16W, 5%	0603	Std	Std	5,650
	R7	10k	Resistor, Chip, 10kΩ 1/16W, 5%	0603	Std	Std	5,650
1	R8	15.6k	Resistor, Chip, 2k49Ω, 1/16W, 5%	0603	Std	Std	5,650
1	R9	4.99k	Resistor, Chip, 4k99Ω, 1/16W, 5%	0603	Std	Std	5,650
1	U1	TPS74801DRC	IC, 1.5A LDO Regulator with Soft-Start	SON-10	TPS74801DRC	TI	30400
2	U2	TPS74701DRC	IC, 1.5A LDO Regulator with Soft-Start	SON-10	TPS74701DRC	TI	30400
	U3	TPS74701DRC	IC, 1.5A LDO Regulator with Soft-Start	SON-10	TPS74701DRC	TI	30400

Notes: 1. These assemblies are ESD sensitive, ESD precautions shall be observed.

^{2.} These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

^{3.} These assemblies must comply with workmanship standards IPC-A-610 Class 2.

Ref designators marked with an asterisk (***) cannot be substituted.
All other components can be substituted with equivalent MFG's components.



www.ti.com Test Result

5 Test Result

The startup waveform, shown in Figure 2, demonstrates that the required sequencing order is followed.

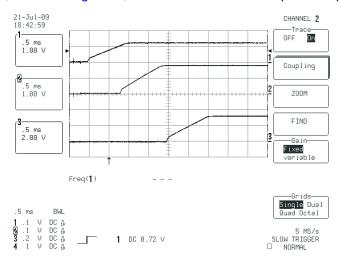


Figure 2. Shows Sequencing in Start up Waveform

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